

# Curriculum Vitae

## GONG Feng

Male|08/27/1988 |Chinese

Materials Research Lab, Department of Mechanical Engineering  
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### Education

2011.07-2015.06 National University of Singapore (NUS), Mechanical Engineering Department,	PhD
2013.03-2013.08 University of Oklahoma, School of Chemical, Biological and Materials Engineering,	Short-term Scholar
2007.09-2011.07 Sichuan University (SCU), School of Manufacturing Science and Engineering,	Fist-Honor Bachelor

### Research Projects, Fields, and Skills

#### Research Projects:

2013.07-2015.06 Theoretical study on thermal transport properties in carbon nanotube (CNT)-polymer composites  
2012.03-2013.07 Multi-scale modeling of cancer photothermal therapy using carbon nanomaterials and laser  
2011.07-2012.03 Computational modeling of thermal transport in multi-scale carbon fibers

**Research Fields:** Carbon nanomaterials, Computational material science and engineering, Mechanical engineering, Monte Carlo Simulation, Molecular dynamics simulation, Material physics, Micro- and nano-scale heat transfer, Cancer photothermal therapy

**Computer:** Fortran, Matlab, Visual C, Visual Basic programming, Finite Element software: Ansys, AutoCAD, Solidworks, ProE

### Selected Scholarships and Awards

2011.07-2015.07 NUS Research Scholarship	2013.03-2013.08 Short-term Scholar to University of Oklahoma
2010.10 Second Prize of “National Undergraduate Mechanical innovation design competition” in Sichuan Province	
2009.10 National First Prize of “National Undergraduate Engineering Training Integration Ability Competition”	
2010.06 “Creative Talents” of Sichuan University	2009.09 National Scholarship of China

### Publications (IF: Impact Factor)

- [1] **Gong F.**; Papavassiliou D. V.; Duong H. M.; Carbon Nanotube Bundle and Thermal Contact Resistance in Thermal Transport of Three-Phase Polymer Composites, *J. Phys. Chem. C*. (2015) DOI: 10.1021/acs.jpcc.5b00651. (IF: 4.835)
- [2] **Gong F.**, Tam Y. S., Nguyen S. T., Duong H. M, Prediction of Thermal Resistances and Thermal Conductivities of Carbon Nanotube Aerogels in Various Permeated Gases, *Chem. Phys. Lett.*, 2015, in press. (IF: 2.008)
- [3] Fan Z.<sup>#</sup>; **Gong F.**<sup>#</sup>; Nguyen S. T.; Duong H. M; Advanced Multi-properties of Graphene Aerogel (GA) – PMMA Composites: Experiments and Modelling , *Carbon*, 81, 396-404 (2015). (<sup>#</sup>Contribute equally. IF : 6.638)
- [4] **Gong F.**; Bui K.; Papavassiliou D. V.; Duong H. M.; Thermal transport phenomena and limitations in heterogeneous polymer composites containing carbon nanotubes and inorganic nanoparticles, *Carbon* 78, 305-316 (2014). (IF : 6.638)
- [5] **Gong F.** et al. Mesoscopic Modeling of Cancer Photothermal Therapy Using Single Walled Carbon Nanotubes and Near Infrared Radiation: An Off-lattice Monte Carlo Insight, *Nanotechnology* 25, 205101 (2014). (IF: 3.842)
- [6] **Gong F.** et al. Off-lattice Monte Carlo Simulation of Heat Transfer through Carbon Nanotube Multiphase System Taking into Account Thermal Boundary Resistances, *Numer. Heat Transfer Part A* 65, 1023-1043 (2014). (IF: 1.847)
- [7] **Gong F.** et al. Computational Study on Anisotropic Thermal Characterization of Multi-scale Wires Using Transient Electrothermal Technique, *Int. J. Therm. Sci.* 77, 165-171 (2014). (IF: 2.732)
- [8] Tan J. W.; Cheng Y.; Yap S. G.; **Gong F.**; Nguyen S. T.; Duong H. M.; Anisotropic heat transfer prediction of multiscale wires using pulse laser thermal relaxation technique, *Chem. Phys. Lett.* 555, 239-246 (2013). (IF: 2.008)

### Social and Other Academic Activities

2013.12 4<sup>th</sup> International Symposium on Computational Mechanics, Singapore, Organizer  
2013.10 23<sup>rd</sup> International Workshop on Computational Mechanics of Materials, Singapore, Organizer  
2013.07-2015.07 Graduate Tutor of Heat Transfer Module, NUS: conduct tutorials for 350+ undergraduate students  
2009.10 10<sup>th</sup> Western China International Fair, Translator                      2008.05 Volunteer after Wenchuan Great Earthquake